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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "<u>Embedded - Microcontrollers</u>"

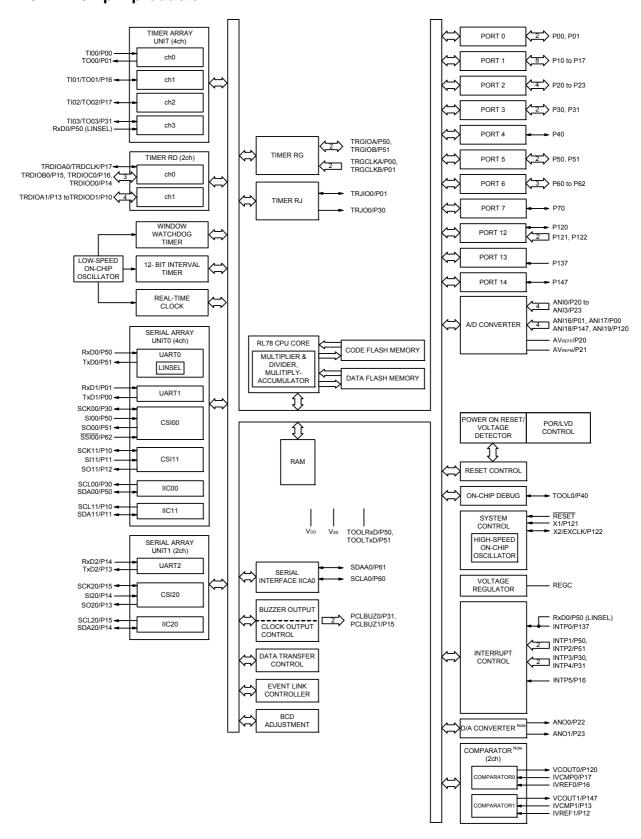
Details	
Product Status	Obsolete
Core Processor	RL78
Core Size	16-Bit
Speed	32MHz
Connectivity	CSI, I ² C, LINbus, UART/USART
Peripherals	DMA, LVD, POR, PWM, WDT
Number of I/O	82
Program Memory Size	256KB (256K x 8)
Program Memory Type	FLASH
EEPROM Size	8K x 8
RAM Size	24K x 8
Voltage - Supply (Vcc/Vdd)	1.6V ~ 5.5V
Data Converters	A/D 20x8/10b; D/A 2x8b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	100-LQFP
Supplier Device Package	100-LQFP (14x20)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f104pjafa-v0

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Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

RL78/G14 1. OUTLINE

1.5.2 32-pin products



Note Mounted on the 96 KB or more code flash memory products.

RL78/G14 1. OUTLINE

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		30-pin	32-pin	36-pin	40-pin				
l ¹	tem	R5F104Ax	R5F104Bx	R5F104Cx	R5F104Ex				
		(x = A, C to E)	(x = A, C to E)	(x = A, C to E)	(x = A, C to E)				
Clock output/buzzer	output	2	2	2	2				
		(Main system clock: fma [40-pin products] • 2.44 kHz, 4.88 kHz, 9.7 (Main system clock: fma • 256 Hz, 512 Hz, 1.024	6 kHz, 1.25 MHz, 2.5 MHz IN = 20 MHz operation) 6 kHz, 1.25 MHz, 2.5 MHz	, 5 MHz, 10 MHz	i2.768 kHz				
8/10-bit resolution A	/D converter	8 channels	8 channels	8 channels	9 channels				
Serial interface		[30-pin, 32-pin products] • CSI: 1 channel/UART (UART supporting LIN-bus): 1 channel/simplified I ² C: 1 channel • CSI: 1 channel/UART: 1 channel/simplified I ² C: 1 channel • CSI: 1 channel/UART: 1 channel/simplified I ² C: 1 channel [36-pin, 40-pin products] • CSI: 1 channel/UART (UART supporting LIN-bus): 1 channel/simplified I ² C: 1 channel • CSI: 1 channel/UART: 1 channel/simplified I ² C: 2 channel • CSI: 2 channels/UART: 1 channel/simplified I ² C: 2 channels							
	I ² C bus	1 channel	1 channel	1 channel	1 channel				
Data transfer contro	ller (DTC)	28 sources			29 sources				
Event link controller	(ELC)	Event input: 19 Event input: 20 Event trigger output: 7 Event trigger output: 7							
Vectored interrupt	Internal	24	24	24	24				
sources	External	6	6	6	7				
Key interrupt	1	_	_	_	4				
Reset		Reset by RESET pin Internal reset by watchdog timer Internal reset by power-on-reset Internal reset by voltage detector Internal reset by illegal instruction execution Note Internal reset by RAM parity error Internal reset by illegal-memory access							
Power-on-reset circu	uit	 Power-on-reset: 1.51 ±0.04 V (TA = -40 to +85°C)							
Voltage detector		1.63 V to 4.06 V (14 stages)							
On-chip debug funct	ion	Provided			-				
Power supply voltag	e	V _{DD} = 1.6 to 5.5 V (T _A = - V _{DD} = 2.4 to 5.5 V (T _A = -	•						
Operating ambient to	emperature	$T_A = -40 \text{ to } +85^{\circ}\text{C} \text{ (A: Co}$ $T_A = -40 \text{ to } +105^{\circ}\text{C} \text{ (G: In}$	nsumer applications, D: Industrial applications)	dustrial applications),					

Note The illegal instruction is generated when instruction code FFH is executed.

Reset by the illegal instruction execution not is issued by emulation with the in-circuit emulator or on-chip debug emulator.

RL78/G14 1. OUTLINE

[44-pin, 48-pin, 52-pin, 64-pin products (code flash memory 96 KB to 256 KB)]

Caution This outline describes the functions at the time when Peripheral I/O redirection register 0, 1 (PIOR0, 1) are set to 00H.

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					(1/2)					
		44-pin	48-pin	52-pin	64-pin					
	Item	R5F104Fx	R5F104Gx	R5F104Jx	R5F104Lx					
		(x = F to H, J)	(x = F to H, J)	(x = F to H, J)	(x = F to H, J)					
Code flash me	mory (KB)	96 to 256	96 to 256	96 to 256	96 to 256					
Data flash mer	mory (KB)	8	8	8	8					
RAM (KB)		12 to 24 Note 12								
Address space	;	1 MB								
Main system clock	High-speed system clock	HS (high-speed main) HS (high-speed main) LS (low-speed main) n	scillation, external main mode: 1 to 20 MHz (V mode: 1 to 16 MHz (V node: 1 to 8 MHz (VD mode: 1 to 4 MHz (VD	DD = 2.7 to 5.5 V), DD = 2.4 to 5.5 V), DD = 1.8 to 5.5 V),	CCLK)					
	High-speed on-chip oscillator clock (fін)	HS (high-speed main)	HS (high-speed main) mode: 1 to 32 MHz (VDD = 2.7 to 5.5 V), HS (high-speed main) mode: 1 to 16 MHz (VDD = 2.4 to 5.5 V), LS (low-speed main) mode: 1 to 8 MHz (VDD = 1.8 to 5.5 V), LV (low-voltage main) mode: 1 to 4 MHz (VDD = 1.6 to 5.5 V) XT1 (crystal) oscillation, external subsystem clock input (EXCLKS) 32.768 kHz							
Subsystem clo	ck	XT1 (crystal) oscillatio	n, external subsystem o	clock input (EXCLKS) 3	2.768 kHz					
Low-speed on-	-chip oscillator clock	15 kHz (TYP.): V _{DD} = 1	1.6 to 5.5 V							
General-purpo	se register	8 bits × 32 registers (8 bits × 8 registers × 4 banks)								
Minimum instru	uction execution time	0.03125 μs (High-spee	ed on-chip oscillator clo	ck: fін = 32 MHz operat	ion)					
		0.05 μs (High-speed system clock: fмx = 20 MHz operation)								
		30.5 μs (Subsystem cl	ock: fsuв = 32.768 kHz	operation)						
Instruction set		 Data transfer (8/16 bits) Adder and subtractor/logical operation (8/16 bits) Multiplication (8 bits × 8 bits, 16 bits × 16 bits), Division (16 bits ÷ 16 bits, 32 bits ÷ 32 bits) Multiplication and Accumulation (16 bits × 16 bits + 32 bits) Rotate, barrel shift, and bit manipulation (Set, reset, test, and Boolean operation), etc. 								
I/O port	Total	40	44	48	58					
	CMOS I/O	31	34	38	48					
	CMOS input	5	5	5	5					
	CMOS output	_	1	1	1					
	N-ch open-drain I/O (6 V tolerance)	4	4	4	4					
Timer	16-bit timer	8 channels (TAU: 4 channels, Tim	er RJ: 1 channel, Timer	RD: 2 channels, Timer	RG: 1 channel)					
	Watchdog timer	1 channel								
	Real-time clock (RTC)	1 channel								
	12-bit interval timer	1 channel								
	Timer output	Timer outputs: 14 char PWM outputs: 9 chann								

(Note is listed on the next page.)

Absolute Maximum Ratings

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Parameter	Symbols		Conditions	Ratings	Unit
Output current, high	Іон1	Per pin	P00 to P06, P10 to P17, P30, P31, P40 to P47, P50 to P57, P64 to P67, P70 to P77, P80 to P87, P100 to P102, P110, P111, P120, P130, P140 to P147	-40	mA
		Total of all pins	P00 to P04, P40 to P47, P102, P120, P130, P140 to P145	-70	mA
		-170 mA	P05, P06, P10 to P17, P30, P31, P50 to P57, P64 to P67, P70 to P77, P80 to P87, P100, P101, P110, P111, P146, P147	-100	mA
	Іон2	Per pin	P20 to P27, P150 to P156	-0.5	mA
		Total of all pins		-2	mA
Output current, low	lOL1	Per pin	P00 to P06, P10 to P17, P30, P31, P40 to P47, P50 to P57, P64 to P67, P70 to P77, P80 to P87, P100 to P102, P110, P111, P120, P130, P140 to P147	40	mA
		Total of all pins	P00 to P04, P40 to P47, P102, P120, P130, P140 to P145	70	mA
		170 mA	P05, P06, P10 to P17, P30, P31, P50 to P57, P60 to P67, P70 to P77, P80 to P87, P100, P101, P110, P111, P146, P147	100	mA
	lol2	Per pin	P20 to P27, P150 to P156	1	mA
		Total of all pins		5	mA
Operating ambient tem-	TA	In normal c	operation mode	-40 to +85	°C
perature		In flash me	emory programming mode		
Storage temperature	Tstg			-65 to +150	°C

Caution Product quality may suffer if the absolute maximum rating is exceeded even momentarily for any parameter. That is, the absolute maximum ratings are rated values at which the product is on the verge of suffering physical damage, and therefore the product must be used under conditions that ensure that the absolute maximum ratings are not exceeded.

Remark Unless specified otherwise, the characteristics of alternate-function pins are the same as those of the port pins.

2.3 DC Characteristics

2.3.1 Pin characteristics

(TA = -40 to +85°C, 1.6 V \leq EVDD0 = EVDD1 \leq VDD \leq 5.5 V, VSS = EVSS0 = EVSS1 = 0 V)

Items	Symbol	Conditions		MIN.	TYP.	MAX.	Unit
Output current, high Note 1	Іон1	Per pin for P00 to P06, P10 to P17, P30, P31, P40 to P47, P50 to P57, P64 to P67, P70 to P77, P80 to P87, P100 to P102, P110, P111, P120, P130, P140 to P147	1.6 V ≤ EVDD0 ≤ 5.5 V			-10.0 Note 2	mA
		D400 D400 D400 D440 to D445	4.0 V ≤ EVDD0 ≤ 5.5 V			-55.0	mA
		P102, P120, P130, P140 to P145	2.7 V ≤ EV _{DD0} < 4.0 V			-10.0	mA
		(When duty ≤ 70% Note 3)	1.8 V ≤ EV _{DD0} < 2.7 V			-5.0	mA
			1.6 V ≤ EV _{DD0} < 1.8 V			-2.5	mA
		Total of P05, P06, P10 to P17,	4.0 V ≤ EVDD0 ≤ 5.5 V			-80.0	mA
		P30, P31, P50 to P57,	2.7 V ≤ EVDD0 < 4.0 V			-19.0	mA
		P64 to P67, P70 to P77, P80 to P87, P100, P101, P110,	1.8 V ≤ EVDD0 < 2.7 V			-10.0	mA
		P111, P146, P147 (When duty ≤ 70% Note 3)	1.6 V ≤ EVDD0 < 1.8 V			-5.0	mA
		Total of all pins (When duty ≤ 70% Note 3)	1.6 V ≤ EVDD0 ≤ 5.5 V			-135.0 Note 4	mA
	Іон2	Per pin for P20 to P27, 1.6 P150 to P156	1.6 V ≤ VDD ≤ 5.5 V			-0.1 Note 2	mA
		Total of all pins (When duty ≤ 70% Note 3)	1.6 V ≤ VDD ≤ 5.5 V			-1.5	mA

Note 1. Value of current at which the device operation is guaranteed even if the current flows from the EVDDO, EVDD1, VDD pins to an output pin.

Note 3. Specification under conditions where the duty factor $\leq 70\%$.

The output current value that has changed to the duty factor > 70% the duty ratio can be calculated with the following expression (when changing the duty factor from 70% to n%).

• Total output current of pins = (IoH \times 0.7)/(n \times 0.01) <Example> Where n = 80% and IoH = -10.0 mA Total output current of pins = (-10.0 \times 0.7)/(80 \times 0.01) \approx -8.7 mA

However, the current that is allowed to flow into one pin does not vary depending on the duty factor.

A current higher than the absolute maximum rating must not flow into one pin.

Note 4. -100 mA for industrial applications (R5F104xxDxx, R5F104xxGxx).

Caution P00, P02 to P04, P10, P11, P13 to P15, P17, P30, P43 to P45, P50 to P55, P71, P74, P80 to P82, and P142 to P144 do not output high level in N-ch open-drain mode.

Remark Unless specified otherwise, the characteristics of alternate-function pins are the same as those of the port pins.

Note 2. Do not exceed the total current value.

- Note 1. Total current flowing into VDD, EVDD0, and EVDD1, including the input leakage current flowing when the level of the input pin is fixed to VDD, EVDD0, and EVDD1, or Vss, EVss0, and EVss1. The values below the MAX. column include the peripheral operation current. However, not including the current flowing into the A/D converter, D/A converter, comparator, LVD circuit, I/O port, and on-chip pull-up/pull-down resistors and the current flowing during data flash rewrite.
- Note 2. When high-speed on-chip oscillator and subsystem clock are stopped.
- Note 3. When high-speed system clock and subsystem clock are stopped.
- **Note 4.** When high-speed on-chip oscillator and high-speed system clock are stopped. When AMPHS1 = 1 (Ultra-low power consumption oscillation). However, not including the current flowing into the 12-bit interval timer and watchdog timer.
- Note 5. Relationship between operation voltage width, operation frequency of CPU and operation mode is as below.

HS (high-speed main) mode: $2.7 \text{ V} \le \text{V}_{DD} \le 5.5 \text{ V} @ 1 \text{ MHz to } 32 \text{ MHz}$

 $2.4~V \leq V_{DD} \leq 5.5~V \textcircled{@}1~MHz$ to 16 MHz

LS (low-speed main) mode: 1.8 V \leq VDD \leq 5.5 V@1 MHz to 8 MHz LV (low-voltage main) mode: 1.6 V \leq VDD \leq 5.5 V@1 MHz to 4 MHz

- Remark 1. fmx: High-speed system clock frequency (X1 clock oscillation frequency or external main system clock frequency)
- Remark 2. fHoco: High-speed on-chip oscillator clock frequency (64 MHz max.)
 Remark 3. fH: High-speed on-chip oscillator clock frequency (32 MHz max.)
 Remark 4. fsub: Subsystem clock frequency (XT1 clock oscillation frequency)
- Remark 5. Except subsystem clock operation, temperature condition of the TYP. value is TA = 25°C

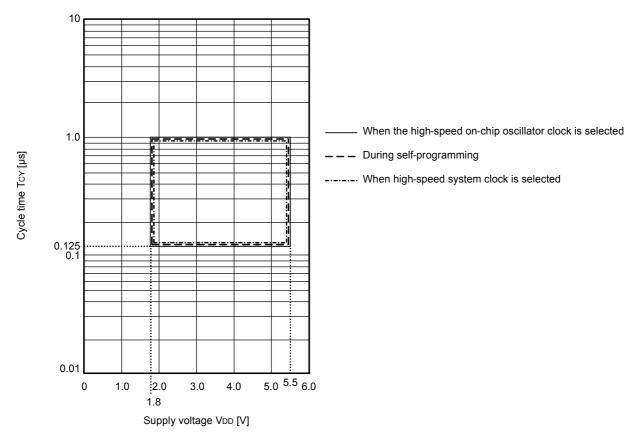
(3) Flash ROM: 384 to 512 KB of 48- to 100-pin products (TA = -40 to +85°C, 1.6 V \leq EVDD0 = EVDD1 \leq VDD \leq 5.5 V, VSS = EVSS0 = EVSS1 = 0 V)

(2/2)

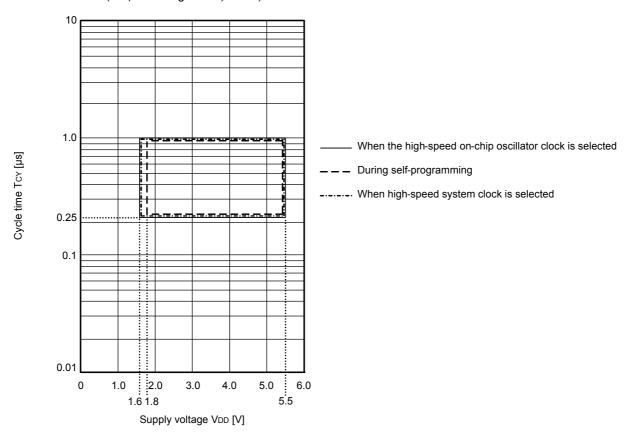
Parameter	Symbol			Conditions		MIN.	TYP.	MAX.	Unit
Supply cur-	IDD2	HALT mode	HS (high-speed main)	fHOCO = 64 MHz,	V _{DD} = 5.0 V		0.93	3.32	mA
rent Note 1	Note 2		mode Note 7	fih = 32 MHz Note 4	V _{DD} = 3.0 V		0.93	3.32	
				fHOCO = 32 MHz,	V _{DD} = 5.0 V		0.5	2.63	
				fih = 32 MHz Note 4	V _{DD} = 3.0 V		0.5	2.63	
				fносо = 48 MHz,	V _{DD} = 5.0 V		0.72	2.60	
				fiH = 24 MHz Note 4	V _{DD} = 3.0 V		0.72	2.60	
				fHOCO = 24 MHz,	V _{DD} = 5.0 V		0.42	2.03	
				fih = 24 MHz Note 4	V _{DD} = 3.0 V		0.42	2.03	
				fHOCO = 16 MHz,	V _{DD} = 5.0 V		0.39	1.50	
				fih = 16 MHz Note 4	V _{DD} = 3.0 V		0.39	1.50	
			LS (low-speed main)	fносо = 8 MHz,	V _{DD} = 3.0 V		270	800	μΑ
			mode Note 7	fih = 8 MHz Note 4	V _{DD} = 2.0 V		270	800	
			LV (low-voltage main)	fHOCO = 4 MHz,	V _{DD} = 3.0 V		450	755	μА
			mode Note 7	fih = 4 MHz Note 4	V _{DD} = 2.0 V		450	755	
			HS (high-speed main)	f _{MX} = 20 MHz Note 3,	Square wave input		0.31	1.69	mA
			mode Note 7	V _{DD} = 5.0 V	Resonator connection		0.41	1.91	
				f _{MX} = 20 MHz Note 3,	Square wave input		0.31	1.69	
				V _{DD} = 3.0 V	Resonator connection		0.41	1.91	
				f _{MX} = 10 MHz Note 3,	Square wave input		0.21	0.94	
				V _{DD} = 5.0 V	Resonator connection		0.26	1.02	
				f _{MX} = 10 MHz Note 3,	Square wave input		0.21	0.94]
				V _{DD} = 3.0 V	Resonator connection		0.26	1.02	
			LS (low-speed main)	fmx = 8 MHz Note 3,	Square wave input		110	610	μΑ
			mode Note 7	V _{DD} = 3.0 V	Resonator connection		150	660	
				f _{MX} = 8 MHz Note 3,	Square wave input		110	610	
				V _{DD} = 2.0 V	Resonator connection		150	660	
			Subsystem clock oper-	fsuB = 32.768 kHz Note 5,	Square wave input		0.31		μΑ
			ation	TA = -40°C	Resonator connection		0.50		
				fsuB = 32.768 kHz Note 5,	Square wave input		0.38	0.76	
				TA = +25°C	Resonator connection		0.57	0.95	
				fsuB = 32.768 kHz Note 5,	Square wave input		0.47	3.59	
				TA = +50°C	Resonator connection		0.70	3.78	
				fsuB = 32.768 kHz Note 5,	Square wave input		0.80	6.20	
				T _A = +70°C	Resonator connection		1.00	6.39	
				fsuB = 32.768 kHz Note 5,	Square wave input		1.65	10.56	
				T _A = +85°C	Resonator connection		1.84	10.75	
	IDD3	STOP mode	TA = -40°C				0.19		μА
	Note 6	Note 8	T _A = +25°C				0.30	0.59	
			TA = +50°C				0.41	3.42	
			T _A = +70°C				0.80	6.03	
			T _A = +85°C				1.53	10.39	

(Notes and Remarks are listed on the next page.)

Tcy vs Vdd (LS (low-speed main) mode)



TCY vs VDD (LV (low-voltage main) mode)



(3) During communication at same potential (CSI mode) (master mode, SCKp... internal clock output) (TA = -40 to +85°C, 1.6 V \leq EVDD0 = EVDD1 \leq VDD \leq 5.5 V, Vss = EVss0 = EVss1 = 0 V)

Parameter	Symbol		Conditions	HS (high-s main) mo		LS (low-speed mode	d main)	LV (low-vol	•	Unit
				MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	
SCKp cycle time	tkcy1	tkcy1 ≥ 4/fclk	2.7 V ≤ EVDD0 ≤ 5.5 V	125		500		1000		ns
			2.4 V ≤ EVDD0 ≤ 5.5 V	250		500		1000		ns
			1.8 V ≤ EV _{DD0} ≤ 5.5 V	500		500		1000		ns
			1.7 V ≤ EV _{DD0} ≤ 5.5 V	1000		1000		1000		ns
			1.6 V ≤ EV _{DD0} ≤ 5.5 V	_		1000		1000		ns
SCKp high-/low-level	tĸнı,	4.0 V ≤ EVDD0	≤ 5.5 V	tkcy1/2 - 12		tkcy1/2 - 50		tkcy1/2 - 50		ns
width	tKL1	2.7 V ≤ EVDD0	≤ 5.5 V	tkcy1/2 - 18		tkcy1/2 - 50		tkcy1/2 - 50		ns
		2.4 V ≤ EVDD0	≤ 5.5 V	tkcy1/2 - 38		tkcy1/2 - 50		tkcy1/2 - 50		ns
		1.8 V ≤ EVDD0	≤ 5.5 V	tkcy1/2 - 50		tkcy1/2 - 50		tkcy1/2 - 50		ns
		1.7 V ≤ EVDD0	≤ 5.5 V	tkcy1/2 - 100		tkcy1/2 - 100		tkcy1/2 - 100		ns
		1.6 V ≤ EVDD0	≤ 5.5 V	_		tkcy1/2 - 100		tkcy1/2 - 100		ns
SIp setup time	tsıĸ1	4.0 V ≤ EVDD0	≤ 5.5 V	44		110		110		ns
(to SCKp↑) Note 1		2.7 V ≤ EVDD0	≤ 5.5 V	44		110		110		ns
		2.4 V ≤ EVDD0	≤ 5.5 V	75		110		110		ns
		1.8 V ≤ EVDD0	≤ 5.5 V	110		110		110		ns
		1.7 V ≤ EVDD0	≤ 5.5 V	220		220		220		ns
		1.6 V ≤ EVDD0	≤ 5.5 V	_		220		220		ns
SIp hold time	tksıı	1.7 V ≤ EVDD0	≤ 5.5 V	19		19		19		ns
(from SCKp↑) Note 2		1.6 V ≤ EVDD0	≤ 5.5 V	_		19		19		ns
Delay time from SCKp↓ to SOp output Note 3	tkso1	1.7 V ≤ EV _{DD0} C = 30 pF Note			25		25		25	ns
I NOTE 3		1.6 V ≤ EVDD0 C = 30 pF Note			_		25		25	ns

- Note 1. When DAPmn = 0 and CKPmn = 0, or DAPmn = 1 and CKPmn = 1. The Slp setup time becomes "to SCKp↓" when DAPmn = 0 and CKPmn = 1, or DAPmn = 1 and CKPmn = 0.
- Note 2. When DAPmn = 0 and CKPmn = 0, or DAPmn = 1 and CKPmn = 1. The SIp hold time becomes "from SCKp↓" when DAPmn = 0 and CKPmn = 1, or DAPmn = 1 and CKPmn = 0.
- Note 3. When DAPmn = 0 and CKPmn = 0, or DAPmn = 1 and CKPmn = 1. The delay time to SOp output becomes "from SCKp↑" when DAPmn = 0 and CKPmn = 1, or DAPmn = 1 and CKPmn = 0.
- Note 4. C is the load capacitance of the SCKp and SOp output lines.
- Caution Select the normal input buffer for the SIp pin and the normal output mode for the SOp pin and SCKp pin by using port input mode register g (PIMg) and port output mode register g (POMg).
- **Remark 1.** p: CSI number (p = 00, 01, 10, 11, 20, 21, 30, 31), m: Unit number (m = 0, 1), n: Channel number (n = 0 to 3), g: PIM number (g = 0, 1, 3 to 5, 14)
- Remark 2. fmck: Serial array unit operation clock frequency
 (Operation clock to be set by the CKSmn bit of serial mode register mn (SMRmn). m: Unit number, n: Channel number (mn = 00 to 03, 10 to 13))

(5) During communication at same potential (simplified I²C mode)

(TA = -40 to +85°C, 1.6 V \leq EVDD0 = EVDD1 \leq VDD \leq 5.5 V, VSS = EVSS0 = EVSS1 = 0 V)

(2/2)

Parameter	Symbol	Conditions	HS (high-speed mode	main)	LS (low-speed m	nain)	LV (low-voltage r mode	main)	Unit
			MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	
Data setup time (reception)	tsu: dat	$2.7~V \leq EV_{DD0} \leq 5.5~V,$ $C_b = 50~pF,~R_b = 2.7~k\Omega$	1/fmcK + 85 Note 2		1/fmck + 145 Note 2		1/fmck + 145 Note 2		ns
		1.8 V \leq EV _{DD0} \leq 5.5 V, C _b = 100 pF, R _b = 3 kΩ	1/fmck + 145 Note 2		1/fmck + 145 Note 2		1/fmck + 145 Note 2		ns
		$1.8~V \leq EV_{DD0} < 2.7~V,$ $C_b = 100~pF,~R_b = 5~k\Omega$	1/fmck + 230 Note 2		1/fmck + 230 Note 2		1/fmck + 230 Note 2		ns
		$1.7~V \leq EV_{DD0} < 1.8~V,$ $C_b = 100~pF,~R_b = 5~k\Omega$	1/fmck + 290 Note 2		1/fmck + 290 Note 2		1/fmck + 290 Note 2		ns
		$1.6 \ V \le EV_{DD0} < 1.8 \ V,$ $C_b = 100 \ pF, \ R_b = 5 \ k\Omega$	_		1/fmck + 290 Note 2		1/fmck + 290 Note 2		ns
Data hold time (transmission)	thd: dat	$2.7 \text{ V} \leq \text{EV}_{\text{DD0}} \leq 5.5 \text{ V},$ $C_b = 50 \text{ pF}, R_b = 2.7 \text{ k}\Omega$	0	305	0	305	0	305	ns
		1.8 V \leq EV _{DD0} \leq 5.5 V, C _b = 100 pF, R _b = 3 kΩ	0	355	0	355	0	355	ns
		$1.8~V \leq EV_{DD0} < 2.7~V,$ $C_b = 100~pF,~R_b = 5~k\Omega$	0	405	0	405	0	405	ns
		$1.7 \text{ V} \le \text{EV}_{\text{DD0}} < 1.8 \text{ V},$ $C_b = 100 \text{ pF}, R_b = 5 \text{ k}\Omega$	0	405	0	405	0	405	ns
		$1.6 \ V \leq EV_{DD0} < 1.8 \ V,$ $C_b = 100 \ pF, \ R_b = 5 \ k\Omega$	_		0	405	0	405	ns

Note 1. The value must also be equal to or less than fmck/4.

Note 2. Set the fMCK value to keep the hold time of SCLr = "L" and SCLr = "H".

Caution Select the normal input buffer and the N-ch open drain output (VDD tolerance (for the 30- to 52-pin products)/EVDD tolerance (for the 64- to 100-pin products)) mode for the SDAr pin and the normal output mode for the SCLr pin by using port input mode register g (PIMg) and port output mode register h (POMh).

(Remarks are listed on the next page.)

(6) Communication at different potential (1.8 V, 2.5 V, 3 V) (UART mode)

(TA = -40 to +85°C, 1.6 V \leq EVDD0 = EVDD1 \leq VDD \leq 5.5 V, VSS = EVSS0 = EVSS1 = 0 V)

Parameter	Symbol		Conditions	٠ ٠	-speed main) node	,	speed main) node	,	voltage main) mode	Unit
				MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	
Transfer rate		reception	$4.0 \text{ V} \le \text{EV}_{DD0} \le 5.5 \text{ V},$ $2.7 \text{ V} \le \text{V}_{b} \le 4.0 \text{ V}$		f _{MCK} /6 Note 1		f _{MCK} /6 Note 1		f _{MCK} /6 Note 1	bps
			Theoretical value of the maximum transfer rate fmck = fclk Note 4		5.3		1.3		0.6	Mbps
			$2.7 \text{ V} \le \text{EV}_{\text{DD0}} < 4.0 \text{ V},$ $2.3 \text{ V} \le \text{V}_{\text{b}} \le 2.7 \text{ V}$		f _{MCK} /6 Note 1		f _{MCK} /6 Note 1		f _{MCK} /6 Note 1	bps
			Theoretical value of the maximum transfer rate folk Note 4		5.3		1.3		0.6	Mbps
			$1.8 \text{ V} \le \text{EV}_{\text{DD0}} < 3.3 \text{ V},$ $1.6 \text{ V} \le \text{V}_{\text{b}} \le 2.0 \text{ V}$		fмск/6 Notes 1, 2, 3		fмск/6 Notes 1, 2		fмск/6 Notes 1, 2	bps
			Theoretical value of the maximum transfer rate fMCK = fCLK Note 4		5.3		1.3		0.6	Mbps

Note 1. Transfer rate in the SNOOZE mode is 4800 bps only.

However, the SNOOZE mode cannot be used when FRQSEL4 = 1.

Note 2. Use it with $EVDD0 \ge V_b$.

Note 3. The following conditions are required for low voltage interface when EVDDO < VDD.

 $2.4~V \leq EV_{DD0} < 2.7~V;$ MAX. 2.6~Mbps

 $1.8 \text{ V} \leq \text{EV}_{\text{DD0}} < 2.4 \text{ V}$: MAX. 1.3 Mbps

Note 4. The maximum operating frequencies of the CPU/peripheral hardware clock (fcLK) are:

HS (high-speed main) mode: 32 MHz (2.7 V \leq VDD \leq 5.5 V)

16 MHz (2.4 V \leq VDD \leq 5.5 V)

LS (low-speed main) mode: 8 MHz (1.8 V \leq VDD \leq 5.5 V) LV (low-voltage main) mode: 4 MHz (1.6 V \leq VDD \leq 5.5 V)

Caution Select the TTL input buffer for the RxDq pin and the N-ch open drain output (VDD tolerance (for the 30- to 52-pin products)/EVDD tolerance (for the 64- to 100-pin products)) mode for the TxDq pin by using port input mode register g (PIMg) and port output mode register g (POMg). For VIH and VIL, see the DC characteristics with TTL input buffer selected.

Remark 1. Vb [V]: Communication line voltage

Remark 2. q: UART number (q = 0 to 3), g: PIM and POM number (g = 0, 1, 5, 14)

Remark 3. fmck: Serial array unit operation clock frequency

(Operation clock to be set by the CKSmn bit of serial mode register mn (SMRmn). m: Unit number,

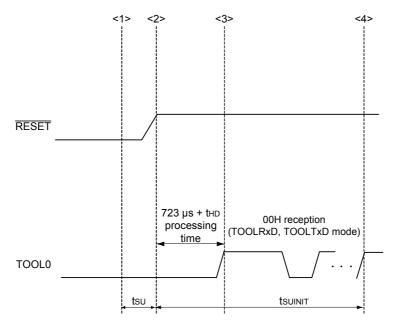
n: Channel number (mn = 00 to 03, 10 to 13)

Remark 4. UART2 cannot communicate at different potential when bit 1 (PIOR01) of peripheral I/O redirection register 0 (PIOR0) is

2.10 Timing of Entry to Flash Memory Programming Modes

(TA = -40 to +85°C, 1.8 V \leq EVDD0 = EVDD1 \leq VDD \leq 5.5 V, Vss = EVss0 = EVss1 = 0 V)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
How long from when an external reset ends until the initial communication settings are specified	tsuinit	POR and LVD reset must end before the external reset ends.			100	ms
How long from when the TOOL0 pin is placed at the low level until an external reset ends	tsu	POR and LVD reset must end before the external reset ends.	10			μs
How long the TOOL0 pin must be kept at the low level after an external reset ends (excluding the processing time of the firmware to control the flash memory)	thD	POR and LVD reset must end before the external reset ends.	1			ms



- <1> The low level is input to the TOOL0 pin.
- <2> The external reset ends (POR and LVD reset must end before the external reset ends).
- <3> The TOOL0 pin is set to the high level.
- <4> Setting of the flash memory programming mode by UART reception and complete the baud rate setting.

Remark tsuinit. The segment shows that it is necessary to finish specifying the initial communication settings within 100 ms from when the external resets end.

tsu: How long from when the TOOL0 pin is placed at the low level until a pin reset ends
thd: How long to keep the TOOL0 pin at the low level from when the external resets end
(excluding the processing time of the firmware to control the flash memory)

3.3 DC Characteristics

3.3.1 Pin characteristics

 $(TA = -40 \text{ to } +105^{\circ}C, 2.4 \text{ V} \le EVDD0 = EVDD1 \le VDD \le 5.5 \text{ V}, VSS = EVSS0 = EVSS1 = 0 \text{ V})$

Items	Symbol	Conditions		MIN.	TYP.	MAX.	Unit
Output current, high Note 1	Іон1	Per pin for P00 to P06, P10 to P17, P30, P31, P40 to P47, P50 to P57, P64 to P67, P70 to P77, P80 to P87, P100 to P102, P110, P111, P120, P130, P140 to P147	2.4 V ≤ EVDD0 ≤ 5.5 V			-3.0 Note 2	mA
		Total of P00 to P04, P40 to P47,	4.0 V ≤ EVDD0 ≤ 5.5 V			-30.0	mA
		P102, P120, P130, P140 to P145	2.7 V ≤ EVDD0 < 4.0 V			-10.0	mA
		(When duty ≤ 70% Note 3)	2.4 V ≤ EVDD0 < 2.7 V			-5.0	mA
		Total of P05, P06, P10 to P17,	4.0 V ≤ EVDD0 ≤ 5.5 V			-30.0	mA
		P30, P31, P50 to P57,	2.7 V ≤ EVDD0 < 4.0 V			-19.0	mA
		P64 to P67, P70 to P77, P80 to P87, P100, P101, P110, P111, P146, P147 (When duty ≤ 70% Note 3)	2.4 V ≤ EVDD0 < 2.7 V			-10.0	mA
		Total of all pins (When duty ≤ 70% Note 3)	2.4 V ≤ EVDD0 ≤ 5.5 V			-60.0	mA
	Іон2	Per pin for P20 to P27, P150 to P156	2.4 V ≤ VDD ≤ 5.5 V			-0.1 Note 2	mA
		Total of all pins (When duty ≤ 70% Note 3)	2.4 V ≤ VDD ≤ 5.5 V			-1.5	mA

Note 1. Value of current at which the device operation is guaranteed even if the current flows from the EVDD0, EVDD1, VDD pins to an output pin.

Note 3. Specification under conditions where the duty factor $\leq 70\%$.

The output current value that has changed to the duty factor > 70% the duty ratio can be calculated with the following expression (when changing the duty factor from 70% to n%).

• Total output current of pins = (IoH × 0.7)/(n × 0.01) <Example> Where n = 80% and IoH = -10.0 mA

Total output current of pins = (-10.0 × 0.7)/(80 × 0.01) ≈ -8.7 mA

However, the current that is allowed to flow into one pin does not vary depending on the duty factor.

A current higher than the absolute maximum rating must not flow into one pin.

Caution P00, P02 to P04, P10, P11, P13 to P15, P17, P30, P43 to P45, P50 to P55, P71, P74, P80 to P82, and P142 to P144 do not output high level in N-ch open-drain mode.

Remark Unless specified otherwise, the characteristics of alternate-function pins are the same as those of the port pins.

Note 2. Do not exceed the total current value.

(TA = -40 to +105°C, 2.4 V \leq EVDD0 = EVDD1 \leq VDD \leq 5.5 V, VSS = EVSS0 = EVSS1 = 0 V)

(2/5)

Items	Symbol	Conditions		MIN.	TYP.	MAX.	Unit
Output current, low Note 1	loL1	Per pin for P00 to P06, P10 to P17, P30, P31, P40 to P47, P50 to P57, P64 to P67, P70 to P77, P80 to P87, P100 to P102, P110, P111, P120, P130, P140 to P147				8.5 Note 2	mA
		Per pin for P60 to P63				15.0 Note 2	mA
		Total of P00 to P04, P40 to P47,	4.0 V ≤ EVDD0 ≤ 5.5 V			40.0	mA
		P102, P120, P130, P140 to P145	2.7 V ≤ EV _{DD0} < 4.0 V			15.0	mA
		(When duty ≤ 70% Note 3) 2.4	2.4 V ≤ EVDD0 < 2.7 V			9.0	mA
		Total of P05, P06, P10 to P17,	4.0 V ≤ EVDD0 ≤ 5.5 V			40.0	mA
		P30, P31, P50 to P57, P60 to P67, P70 to P77,	2.7 V ≤ EV _{DD0} < 4.0 V			35.0	mA
		P80 to P87, P70 to P77, P80 to P87, P100, P101, P110, P111, P146, P147 (When duty ≤ 70% Note 3)	2.4 V ≤ EVDD0 < 2.7 V			20.0	mA
		Total of all pins (When duty ≤ 70% ^{Note 3})				80.0	mA
	lOL2	Per pin for P20 to P27, P150 to P156				0.4 Note 2	mA
		Total of all pins (When duty ≤ 70% Note 3)	2.4 V ≤ VDD ≤ 5.5 V			5.0	mA

- Note 1. Value of current at which the device operation is guaranteed even if the current flows from an output pin to the EVsso, EVss1, and Vss pins.
- Note 2. Do not exceed the total current value.
- **Note 3.** Specification under conditions where the duty factor $\leq 70\%$.

The output current value that has changed to the duty factor > 70% the duty ratio can be calculated with the following expression (when changing the duty factor from 70% to n%).

• Total output current of pins = $(IoL \times 0.7)/(n \times 0.01)$ <Example> Where n = 80% and IoL = 10.0 mA Total output current of pins = $(10.0 \times 0.7)/(80 \times 0.01) \approx 8.7$ mA

However, the current that is allowed to flow into one pin does not vary depending on the duty factor.

A current higher than the absolute maximum rating must not flow into one pin.

Remark Unless specified otherwise, the characteristics of alternate-function pins are the same as those of the port pins.

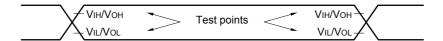
(4) Peripheral Functions (Common to all products)

(TA = -40 to +105°C, 2.4 V \leq EVDD0 = EVDD1 \leq VDD \leq 5.5 V, VSS = EVSS0 = EVSS1 = 0 V)

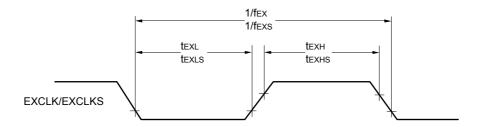
Parameter	Symbol	Conditions		MIN.	TYP.	MAX.	Unit
Low-speed on-chip oscilla- tor operating current	IFIL Note 1				0.20		μΑ
RTC operating current	I _{RTC} Notes 1, 2, 3				0.02		μΑ
12-bit interval timer operat- ing current	IT Notes 1, 2, 4				0.02		μΑ
Watchdog timer operating current	I _{WDT} Notes 1, 2, 5	fi∟ = 15 kHz			0.22		μΑ
A/D converter operating current	I _{ADC} Notes 1, 6	When conversion at maximum speed	Normal mode, AV _{REFP} = V _{DD} = 5.0 V		1.3	1.7	mA
			Low voltage mode, AV _{REFP} = V _{DD} = 3.0 V		0.5	0.7	mA
A/D converter reference voltage current	IADREF Note 1				75.0		μА
Temperature sensor operating current	ITMPS Note 1				75.0		μΑ
D/A converter operating current	IDAC Notes 1, 11, 13	Per D/A converter channel				1.5	mA
Comparator operating current	ICMP Notes 1, 12, 13	V _{DD} = 5.0 V, Regulator output voltage = 2.1 V	Window mode		12.5		μА
			Comparator high-speed mode		6.5		μΑ
			Comparator low-speed mode		1.7		μΑ
		V _{DD} = 5.0 V, Regulator output voltage = 1.8 V	Window mode		8.0		μΑ
			Comparator high-speed mode		4.0		μΑ
			Comparator low-speed mode		1.3		μΑ
LVD operating current	I _{LVD} Notes 1, 7				0.08		μΑ
Self-programming operating current	IFSP Notes 1, 9				2.50	12.20	mA
BGO operating current	I _{BGO} Notes 1, 8				2.50	12.20	mA
SNOOZE operating current	I _{SNOZ} Note 1	ADC operation	The mode is performed Note 10		0.50	1.10	mA
			The A/D conversion operations are performed, Low voltage mode, AVREFP = VDD = 3.0 V		1.20	2.04	
		CSI/UART operation			0.70	1.54	
		DTC operation			3.10		

- Note 1. Current flowing to VDD.
- Note 2. When high speed on-chip oscillator and high-speed system clock are stopped.
- Note 3. Current flowing only to the real-time clock (RTC) (excluding the operating current of the low-speed on-chip oscillator and the XT1 oscillator). The supply current of the RL78 microcontrollers is the sum of the values of either IDD1 or IDD2, and IRTC, when the real-time clock operates in operation mode or HALT mode. When the low-speed on-chip oscillator is selected, IFIL should be added. IDD2 subsystem clock operation includes the operational current of the real-time clock.
- Note 4. Current flowing only to the 12-bit interval timer (excluding the operating current of the low-speed on-chip oscillator and the XT1 oscillator). The supply current of the RL78 microcontrollers is the sum of the values of either IDD1 or IDD2, and IIT, when the 12-bit interval timer operates in operation mode or HALT mode. When the low-speed on-chip oscillator is selected, IFIL should be added.

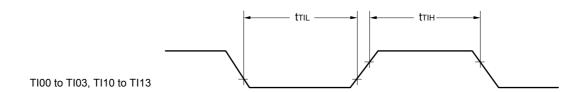
AC Timing Test Points

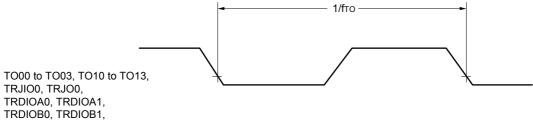


External System Clock Timing



TI/TO Timing





TRDIOCO, TRDIOC1, TRDIODO, TRDIOD1,

TRGIOA, TRGIOB

(3) When reference voltage (+) = VDD (ADREFP1 = 0, ADREFP0 = 0), reference voltage (-) = Vss (ADREFM = 0), target pin: ANI0 to ANI14, ANI16 to ANI20, internal reference voltage, and temperature sensor output voltage

(TA = -40 to +105°C, 2.4 V \leq EVDD0 = EVDD1 \leq VDD \leq 5.5 V, Vss = EVss0 = EVss1 = 0 V, Reference voltage (+) = VDD, Reference voltage (-) = Vss)

Parameter	Symbol	Conditions			TYP.	MAX.	Unit
Resolution	RES			8		10	bit
Overall error Note 1	AINL	10-bit resolution	2.4 V ≤ V _{DD} ≤ 5.5 V		1.2	±7.0	LSB
Conversion time	tconv	10-bit resolution Target pin: ANI0 to ANI14, ANI16 to ANI20	3.6 V ≤ V _{DD} ≤ 5.5 V	2.125		39	μs
			$2.7 \text{ V} \leq \text{V}_{DD} \leq 5.5 \text{ V}$	3.1875		39	μs
			2.4 V ≤ V _{DD} ≤ 5.5 V	17		39	μs
		10-bit resolution Target pin: internal reference voltage, and temperature sensor output voltage (HS (high-speed main) mode)	$3.6 \text{ V} \leq \text{V}_{DD} \leq 5.5 \text{ V}$	2.375		39	μs
			$2.7 \text{ V} \le \text{V}_{DD} \le 5.5 \text{ V}$	3.5625		39	μs
			$2.4 \text{ V} \le \text{V}_{DD} \le 5.5 \text{ V}$	17		39	μs
Zero-scale error Notes 1, 2	Ezs	10-bit resolution	2.4 V ≤ V _{DD} ≤ 5.5 V			±0.60	%FSR
Full-scale error Notes 1, 2	Ers	10-bit resolution	2.4 V ≤ V _{DD} ≤ 5.5 V			±0.60	%FSR
Integral linearity error Note 1	ILE	10-bit resolution	2.4 V ≤ V _{DD} ≤ 5.5 V			±4.0	LSB
Differential linearity error Note 1	DLE	10-bit resolution	$2.4~V \leq V_{DD} \leq 5.5~V$			±2.0	LSB
Analog input voltage	Vain	ANI0 to ANI14		0		VDD	V
		ANI16 to ANI20				EV _{DD0}	٧
		Internal reference voltage (2.4 V ≤ V _{DD} ≤ 5.5 V, HS (high-speed main) mode)			V _{BGR} Note 3		
		Temperature sensor output voltage (2.4 V ≤ V _{DD} ≤ 5.5 V, HS (high-speed main) mode)			V _{TMPS25} Note 3		

Note 1. Excludes quantization error (±1/2 LSB).

Note 2. This value is indicated as a ratio (% FSR) to the full-scale value.

Note 3. Refer to 3.6.2 Temperature sensor characteristics/internal reference voltage characteristic.

(4) When reference voltage (+) = Internal reference voltage (ADREFP1 = 1, ADREFP0 = 0), reference voltage (-) = AVREFM/ANI1 (ADREFM = 1), target pin: ANI0, ANI2 to ANI14, ANI16 to ANI20

(TA = -40 to +105°C, 2.4 V \leq VDD \leq 5.5 V, 1.6 V \leq EVDD = EVDD1 \leq VDD, Vss = EVss0 = EVss1 = 0 V, Reference voltage (+) = VBGR Note 3, Reference voltage (-) = AVREFM = 0 V Note 4, HS (high-speed main) mode)

Parameter	Symbol	Conditions		MIN.	TYP.	MAX.	Unit
Resolution	RES		8				bit
Conversion time	tconv	8-bit resolution	$2.4 \text{ V} \le \text{Vdd} \le 5.5 \text{ V}$	17		39	μs
Zero-scale error Notes 1, 2	Ezs	8-bit resolution	$2.4~V \leq V_{DD} \leq 5.5~V$			±0.60	% FSR
Integral linearity error Note 1	ILE	8-bit resolution	$2.4~V \leq V_{DD} \leq 5.5~V$			±2.0	LSB
Differential linearity error Note 1	DLE	8-bit resolution	$2.4~V \leq V_{DD} \leq 5.5~V$			±1.0	LSB
Analog input voltage	Vain		•	0		V _{BGR} Note 3	V

Note 1. Excludes quantization error (±1/2 LSB).

Note 2. This value is indicated as a ratio (% FSR) to the full-scale value.

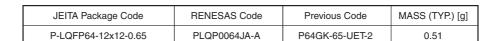
Note 3. Refer to 3.6.2 Temperature sensor characteristics/internal reference voltage characteristic.

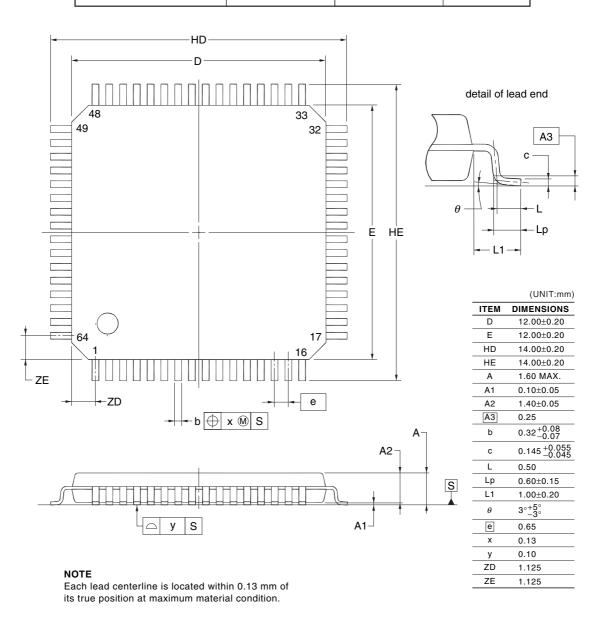
Note 4. When reference voltage (-) = Vss, the MAX. values are as follows.

Zero-scale error: Add $\pm 0.35\%$ FSR to the MAX. value when reference voltage (-) = AVREFM. Integral linearity error: Add ± 0.5 LSB to the MAX. value when reference voltage (-) = AVREFM. Differential linearity error: Add ± 0.2 LSB to the MAX. value when reference voltage (-) = AVREFM.

4.8 64-pin products

R5F104LCAFA, R5F104LDAFA, R5F104LEAFA, R5F104LFAFA, R5F104LGAFA, R5F104LHAFA, R5F104LJAFA R5F104LCDFA, R5F104LDDFA, R5F104LEDFA, R5F104LFDFA, R5F104LGGFA, R5F104LHDFA, R5F104LJDFA R5F104LCGFA, R5F104LDGFA, R5F104LEGFA, R5F104LFGFA, R5F104LGGFA, R5F104LHGFA, R5F104LJGFA R5F104LKAFA, R5F104LLAFA R5F104LKGFA, R5F104LLGFA





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R5F104MKAFB, R5F104MLAFB R5F104MKGFB, R5F104MLGFB

